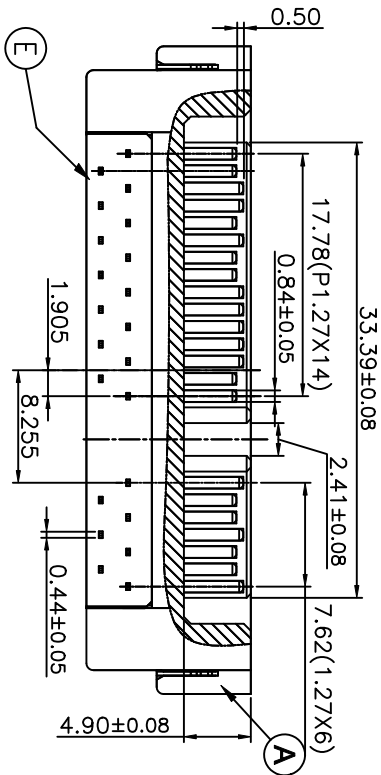
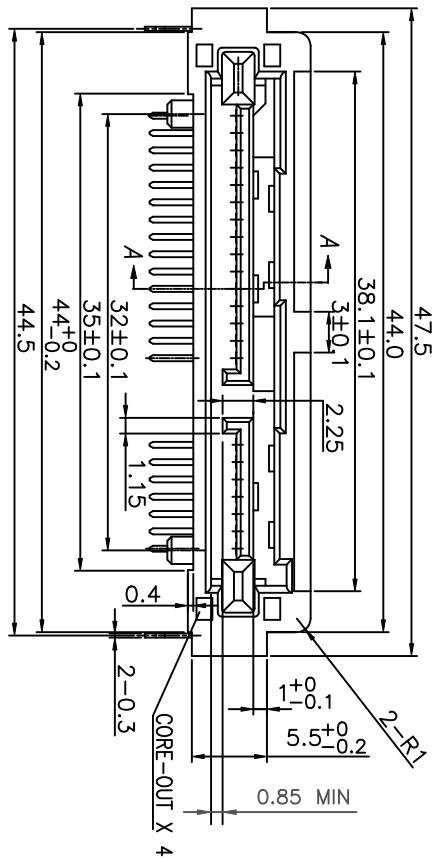
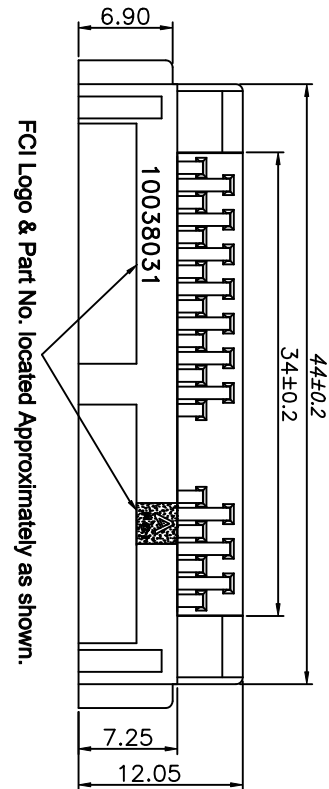
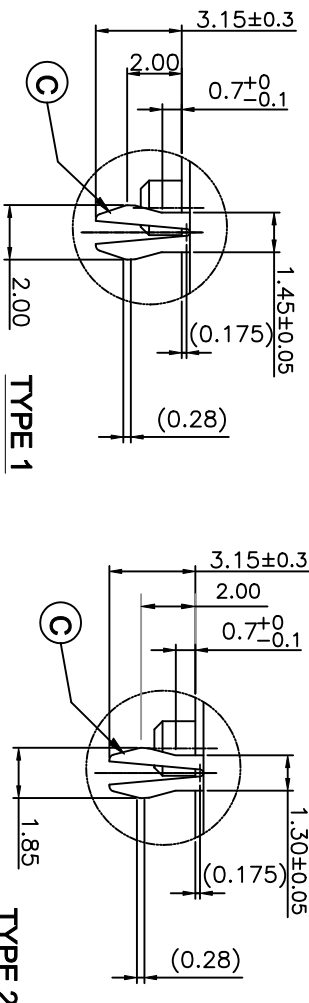
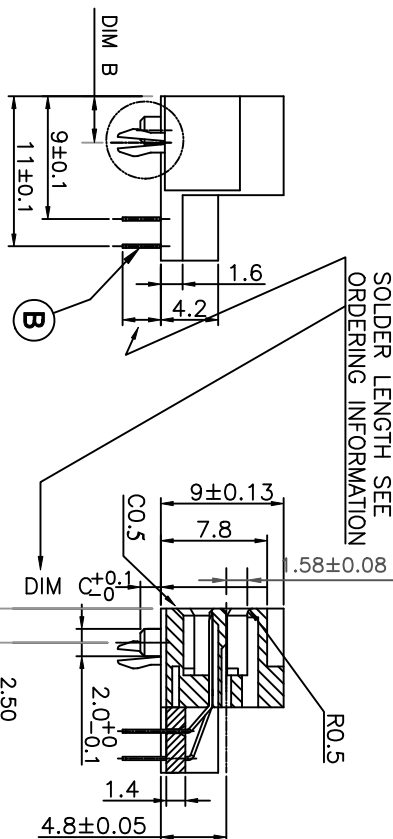
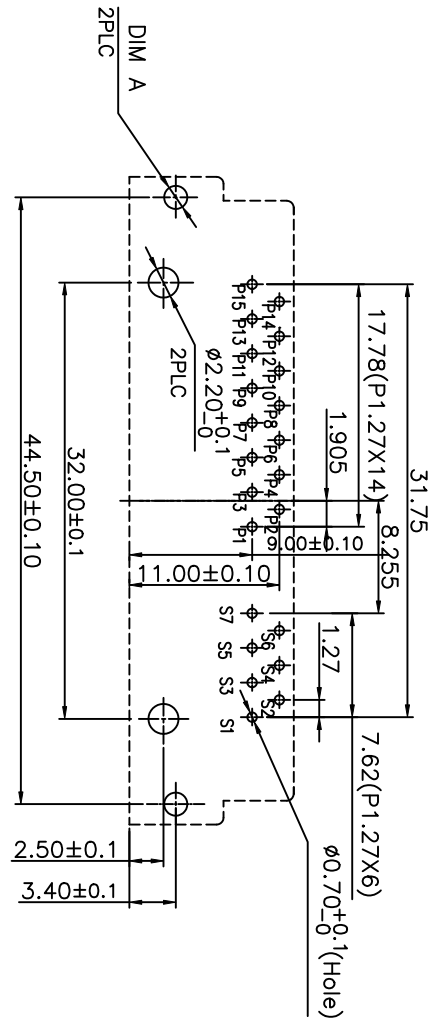




NO.	NAME	MATERIAL	QTY
A	HOUSING	THERMOPLASTIC	1
B	CONTACT	BRASS	22
C	HOLD DOWN	BRASS	2
D	DUST COVER	THERMOPLASTIC	1
E	TAIL GUIDE	THERMOPLASTIC	1

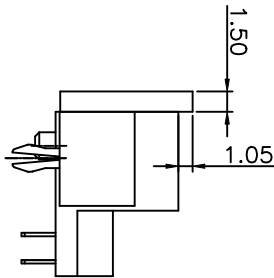
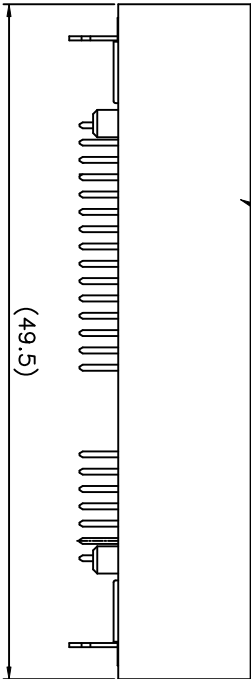


mot'l. code		tolerances unless otherwise specified		CUSTOMER COPY		title		product family		code	
lir	ecn no	dr	date	linear	.XX ± 0.30	projection	MM	scale	NA	product family	S ATA
A	T06-0095	S.Lin	5/11/06	.XXX ± 0.20	.XXX ± 0.10	MM	MM	scale	NA	product family	S ATA
B	T06-0182	S.Lin	04/26/07	.XXX ± 0.10	.XXX ± 0.10	MM	MM	scale	NA	product family	S ATA
C	T08-1198	S.Lin	12/16/08	angles	0° ± 2°	MM	MM	scale	NA	product family	S ATA
D	T08-1199	S.Lin	12/23/08	dr	Sterling Lin	5/10/06	engr	Sterling Lin	5/10/06	product family	S ATA
				chr	Sterling Lin	5/10/06	ppd	HC LIOU	5/10/06	product family	S ATA
sheet	revision	D	D							product family	S ATA
index	sheet	1	2							product family	S ATA



RECOMMENDED PCB LAYOUT(DIP TYPE) T=1.60mm±0.10

Dust Cap (D)



- NOTES :
1. MATERIALS:
 - A. HOUSING:
HIGH TEMPERATURE THERMOPLASTIC UL94V-0.
 - B. CONTACT PIN: COPPER ALLOY .

2. FINISH:
 - A. SATA SIGNAL PINS: (MATING SIDE)
1.27um MINIMUM, 2.54um MAXIMUM NICKEL UNDER PLATE WITH GOLD IN CONTACT AREA.

- B. ALL SOLDER TAILS:
1.91um MINIMUM LEAD-FREE (100%) MATT TIN PLATING.
- C. HOLD DOWN PEG:
1.91um MINIMUM LEAD-FREE (100%) MATT TIN PLATING.

3. THE HOUSING WILL WITHSTAND EXPOSURE TO 260 DEGREE C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

4. PRODUCT SPEC : GS-12-194
PRODUCT SPEC : 110-634 (FOR 10038031-101SLF ONLY)
PACKING SPEC : GS-14-840

5. Order Description: 10038031-X X X X X LF

- BLANK: TYPE 1 HOLD DOWN
1: TYPE 2 HOLD DOWN
S: PRODUCT SPEC 110-634
- Solder Tail Length
0: 2.5mm+5u" Gold at Contact Area
1: 2.8mm+5u" Gold at Contact Area
2: 2.5mm+Gold Flash at Contact Area
3: 2.8mm+Gold Flash at Contact Area
4: 3.25mm+Gold Flash at Contact Area
- 0: With Dust Cap, LCP Housing
1: Without Dust Cap, LCP Housing
2: With Dust Cap, PA 9T Housing
3: Without Dust Cap, PA 9T Housing

	HOLD DOWN	
	TYPE 1	TYPE 2
DIM A	$\phi 1.70^{+0.1}_{-0}$	$\phi 1.50^{+0.1}_{-0}$
DIM B	3.4 ± 0.1	3.9 ± 0.1

SIGNAL SEGMENT		POWER SEGMENT			
S 1	GND	P 1	V ₃₃	P 9	V ₅
S 2	A+	P 2	V ₃₃	P 10	GND
S 3	A-	P 3	V ₃₃	P 11	DAS/DSS
S 4	GND	P 4	GND	P 12	GND
S 5	B-	P 5	GND	P 13	V ₁₂
S 6	B+	P 6	GND	P 14	V ₁₂
S 7	GND	P 7	V ₅	P 15	V ₁₂
		P 8	V ₅		

mot'l. code		tolerances unless otherwise specified		CUSTOMER COPY		FCI	
lfr	ecn no	dr	date	lineor	projection	title	www.fciconnect.com
A	106-0095	S.Lin	5/11/06	.XX ± 0.20	MM	SATA 22 POS, T/H WITH LATCH	
B	106-0182	S.Lin	04/26/07	.XXX ± 0.10	MM		
C	108-1198	S.Lin	12/16/08	0° ± 2°	MM		
D	108-1199	S.Lin	12/23/08		MM		
		engr	Sterling Lin	5/10/06	scale	product family	S ATA
		chr	Sterling Lin	5/10/06	size	dwg no	10038031
		opdd	HC LIU	5/10/06	code	sheet	TWN
sheet	revision	D	D				
index	sheet	1	2				